



—Low Dk and Df—
Coverlay film **“C33 series”**

Example of use

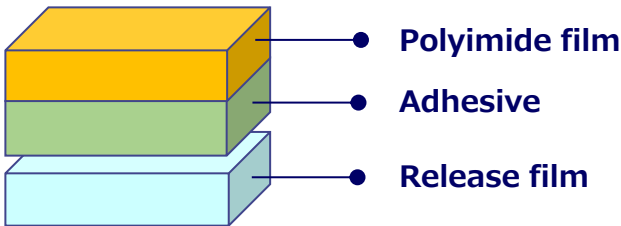
- 5G phone
- Base station antenna
- ADAS (Advanced Driver-Assistance Systems)



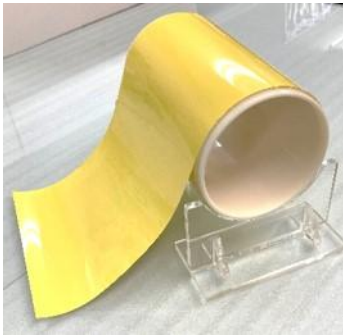
Characteristics

- Low Dielectric constant & Low Dissipation factor.
Dk : 2.60, Df : 0.0026 @10GHz

Product structure



Appearance

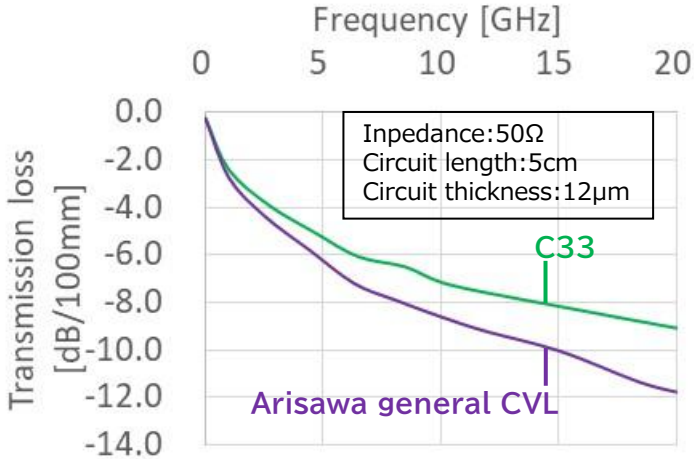


Product Properties

Item		Unit	C33
Polyimide film thickness		μm	12.5
Adhesive thickness		μm	25
Dk (10GHz)	Coverlay	-	2.95
	Adhesive only	-	2.60
Df (10GHz)	Coverlay	-	0.0053
	Adhesive only	-	0.0026
90°Peel strength (Peel 1oz Cu)		N/cm	8.5
Solder heat resistance		-	300

Sample making condition (pressing) :
160℃×3MPa×Keep 45min.

<Transmission loss>



Test sample structure

EMI Shield film		
CVL-PI	12.5μm	
CVL-Adh.	25μm	Cu 12μm
Insulating layer 50μm		
Cu 12μm (GND)		

FCCL:PKHW 2012RAM



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The data in this document are measured values, not for guaranteed.